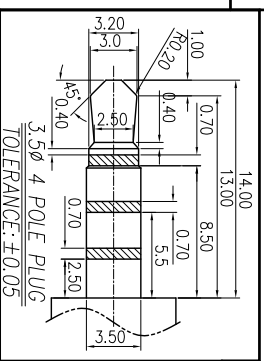
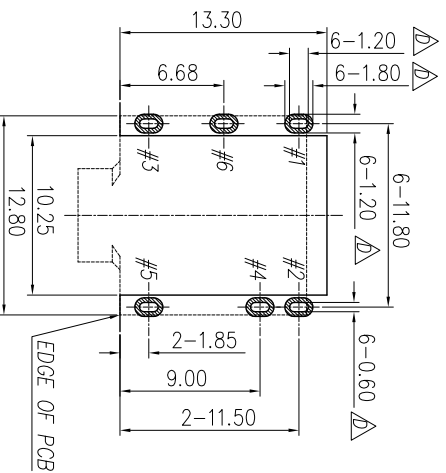
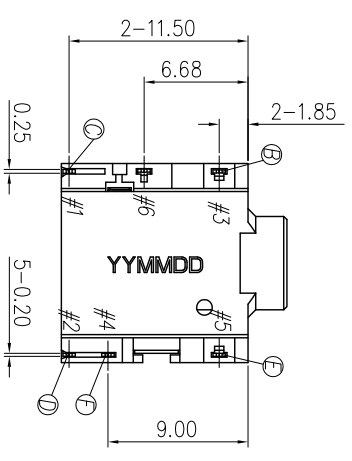
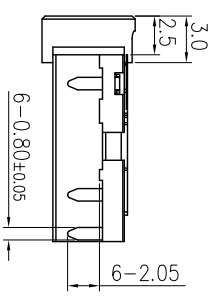
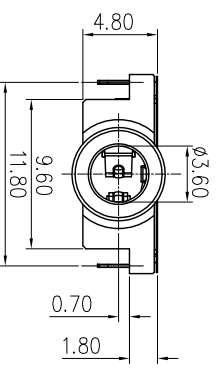
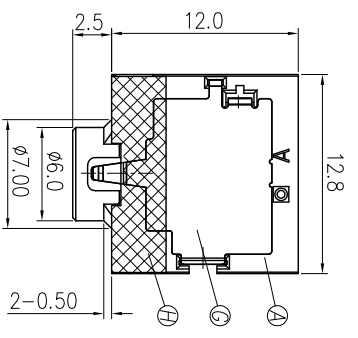
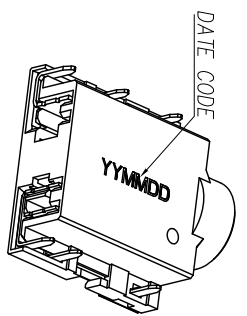
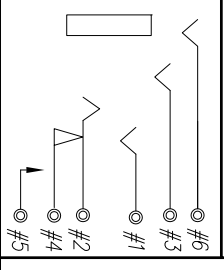


REV.	ECN NO. OR DESCRIPTION	REVISED	DATE
	ECN NO.: 100416	J/ANGUO	2010.10.13
B	設置Shield 接觸部分為鍍金	BILLY	2011.06.13
C	ECN NO: C101049-14 Modify Pinning specification	ZLS	2014.8.12
D	ECN NO.: C14074 MODIFY LAYOUT	ZLS	2014.8.12



SCHEMATIC



SPECIFICATIONS:

- ELECTRICAL CHARACTERISTICS:
 - RATING: 12V AC, 1A DC.
 - CONTACT RESISTANCE: 50mΩ MAX.
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
 - INSULATION RESISTANCE: 100MΩ MIN. MEASURED BY 500 VDC.
- MECHANICAL CHARACTERISTICS:
 - INSERTION FORCE : 0.4~3.0 KGf
 - WITHDRAWAL FORCE : 0.3~2.0 KGf
- LIFE TEST: 5,000 CYCLES MIN.
- OTHER GENERAL SPEC. TO REFER "2SJ2285 SERIES SPEC";
- TO CONFORM TO THE SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK: ☉
- HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
- FOR REFLOW SOLDERING LEAD-FREE PROCESS.
- PACKAGING: TAPE&REEL



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
A	BODY	1	HIGH TEMP THERMOPLASTIC UL 94-V0	BLACK COLOR
B	EARTH	1	COPPER ALLOY 0.20T	GOLD FLASH
C	TIP	1	COPPER ALLOY 0.25T	△ Gold Flash on contact area and Solder teller over Nickel Plated
D	RING	1	COPPER ALLOY 0.20T	GOLD FLASH
E	MAKE TERMINAL	1	COPPER ALLOY 0.20T	△ Gold Flash on contact area and Solder teller over Nickel Plated
F	TRANSFER TERMINAL	1	COPPER ALLOY 0.20T	△ Gold Flash on contact area tallor over Nickel Plated
G	SHIELD	1	COPPER ALLOY 0.20T	△ Gold Flash on contact area tallor over Nickel Plated
H	MYLAR	1	MYLAR 0.075T	

DECIMALS:	ANGLES:
X : ±0.5	X : ±2°
X.X : ±0.3	X.X : ±1°
X.XX : ±0.2	

TITLE	3.5Ø PHONE JACK
DWN	ZLS 14/8/19 PART NO. 2SJ2285-113223
CHKD	BILLY 14/8/19 SCALE 3:1 UNIT: mm
APVD	ZLP 14/8/19 SIZE: A3 SHEET: 10F1 REV: D



Singtron Enterprise Co., Ltd.
信登企業股份有限公司

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